

Examiner's Copy

AN 128:118199 HCA
TI Lead-free **tin** alloy solder having improved thermal fatigue
characteristic
IN Taki, Hideo; Ogura, Toshiaki; Yoshiura, Yozou; Moribayashi, Toshiyuki
PA Nihon Genma Mfg. Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 4 pp.
CODEN: JKXXAF

DT Patent
LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 10034376	A2	19980210	JP 1996-197625	19960726
AB	The Pb-free Sn alloy solder contains Bi 0.1-10, Ag 0.1-5, Cu 0.05-2, Ni 0.0005-0.1, P 0.0005-0.01 and optionally In 0.01-0.5 wt.%.				